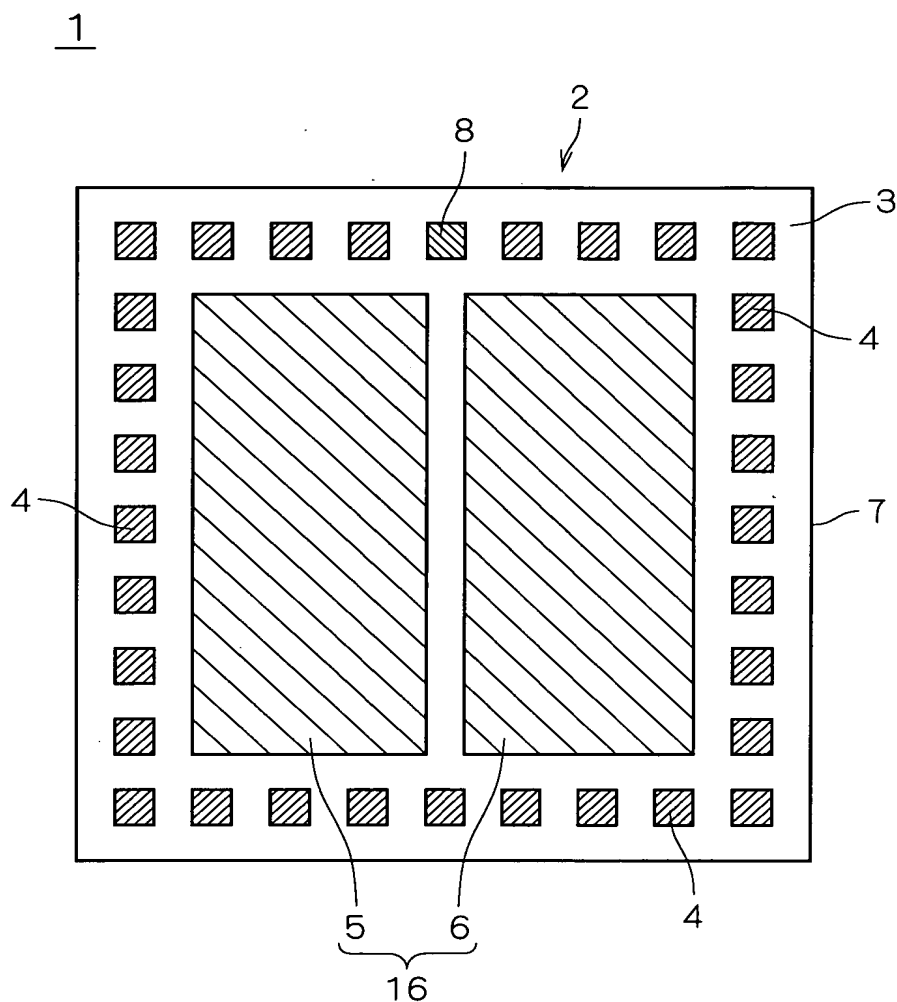


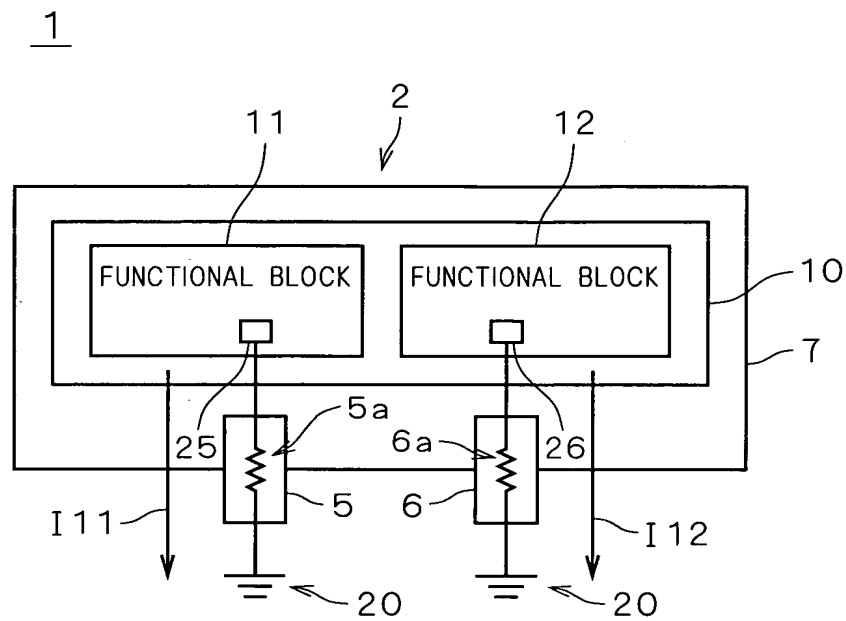
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FIG. 1



- 1: SEMICONDUCTOR DEVICE
- 2: PACKAGE
- 3: MOLDING RESIN
- 4: SIGNAL TERMINALS
- 5, 6, 16: GROUND TERMINALS

FIG. 2



10: SEMICONDUCTOR INTEGRATED CIRCUIT

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FIG. 3

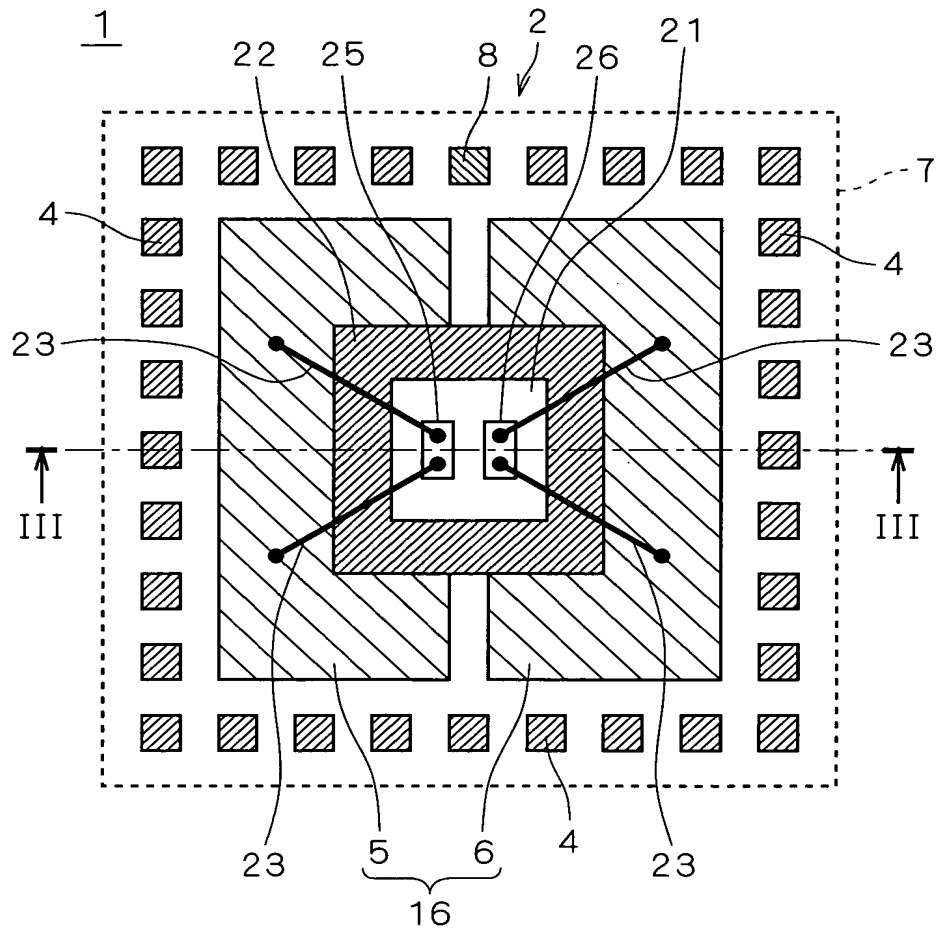


FIG. 4

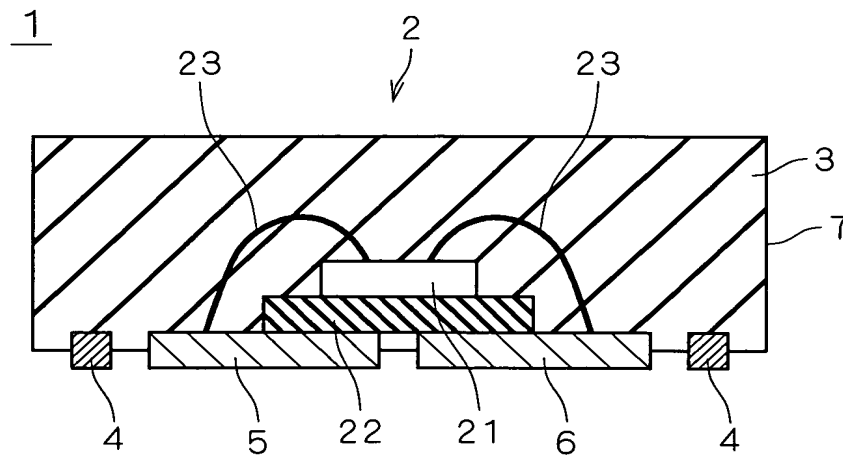
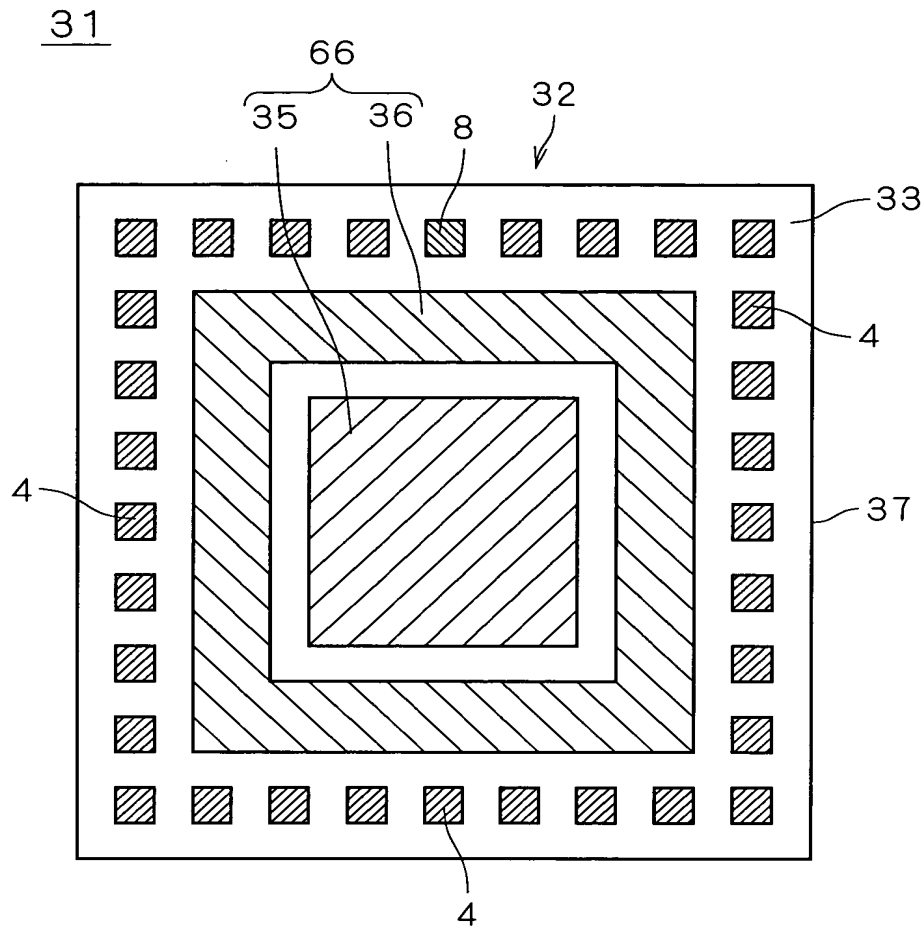


FIG. 5



31: SEMICONDUCTOR DEVICE
32: PACKAGE
33: MOLDING RESIN
35, 36, 66: GROUND TERMINALS

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FIG. 6

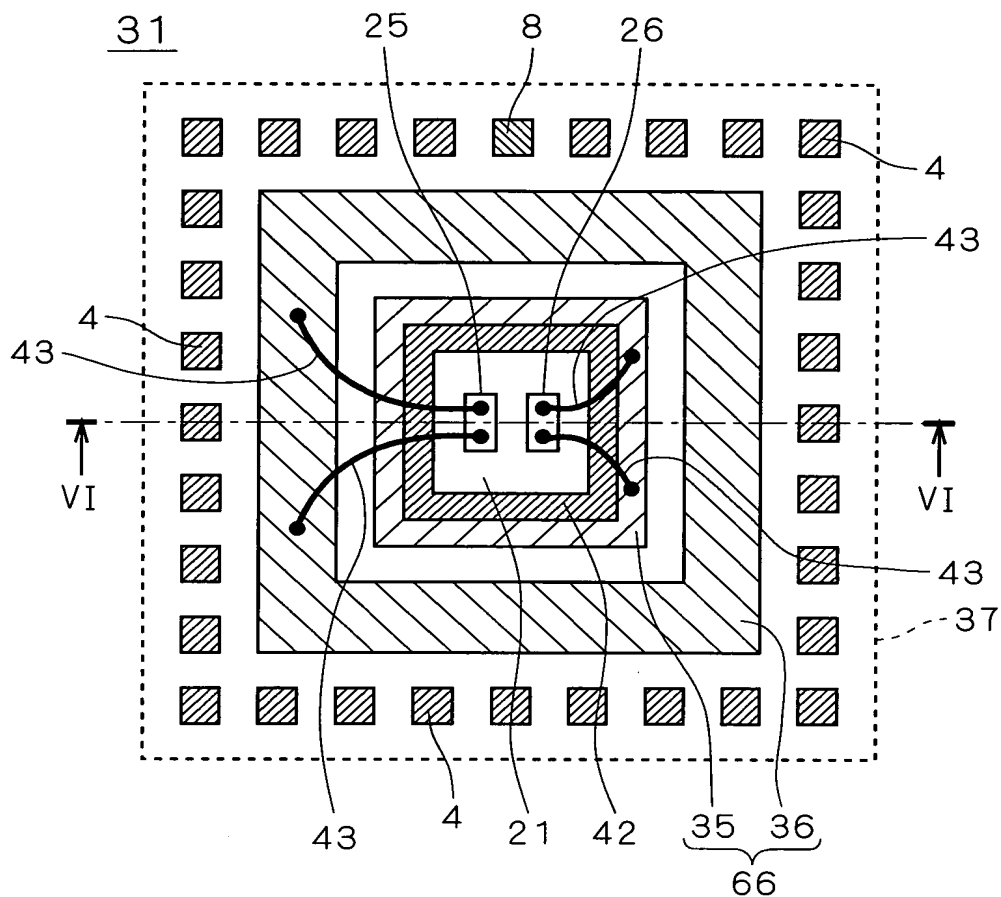
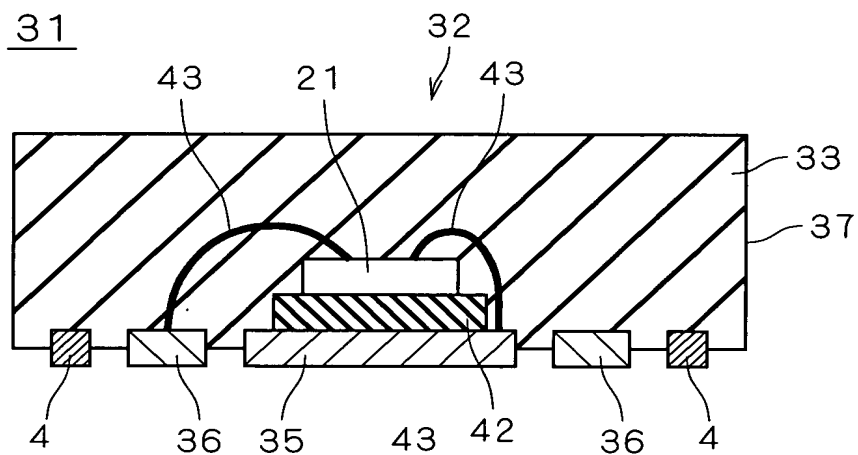
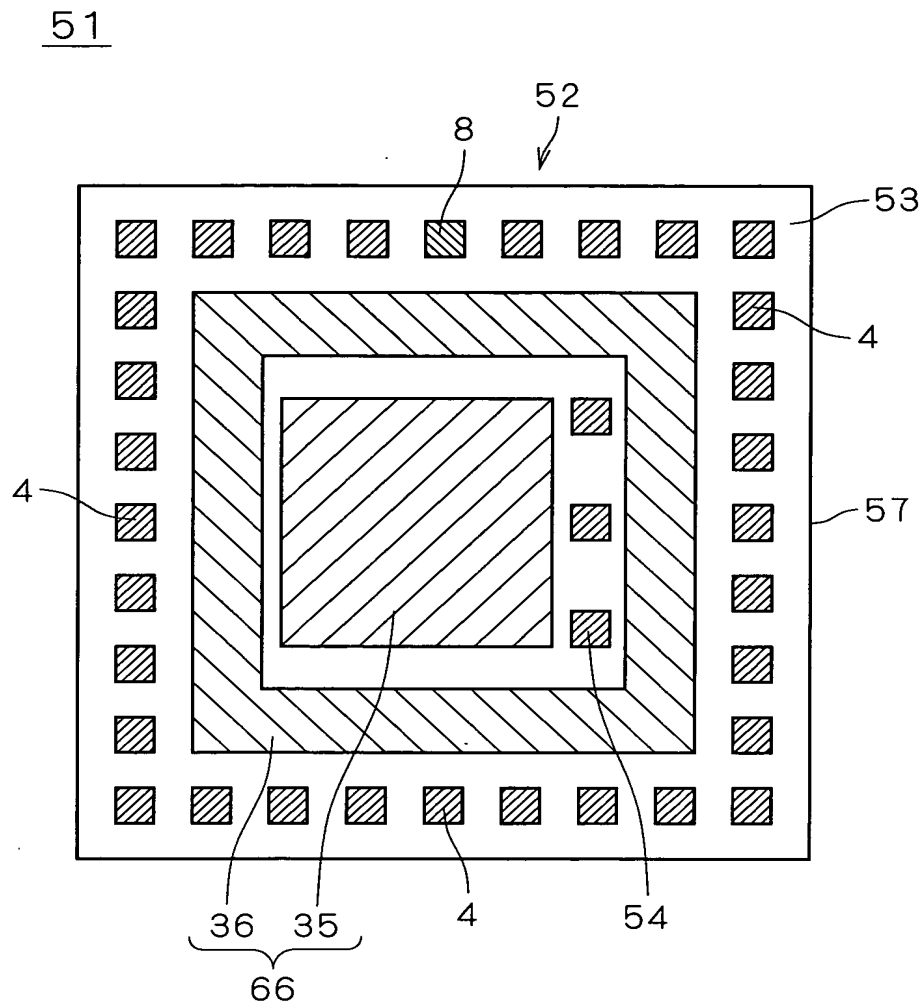


FIG. 7



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FIG. 8



51: SEMICONDUCTOR DEVICE

52: PACKAGE

53: MOLDING RESIN

54: SIGNAL TERMINALS

FIG. 9

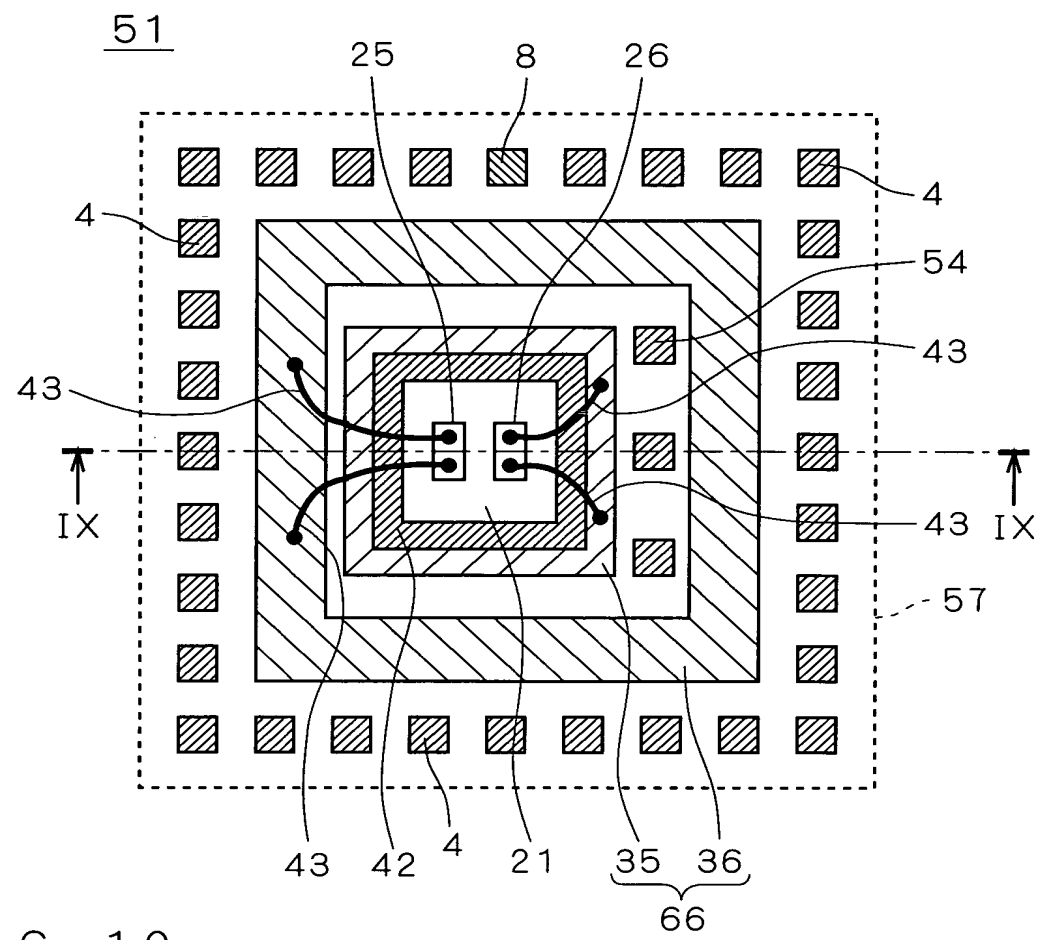
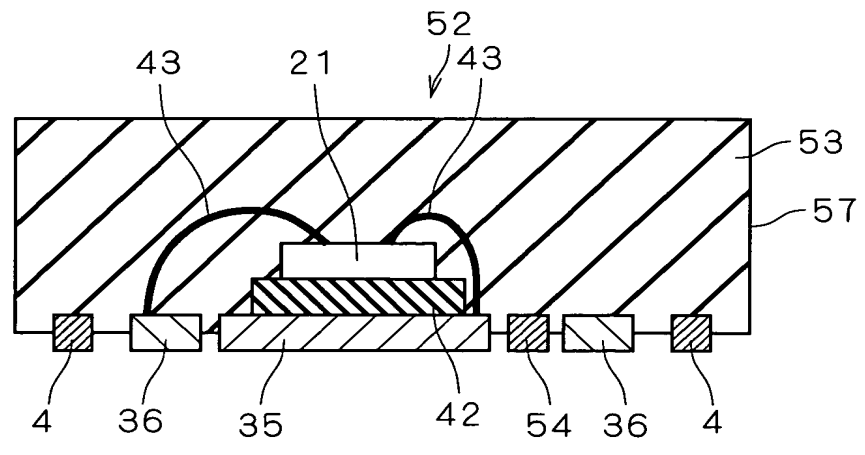


FIG. 10



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FIG. 11

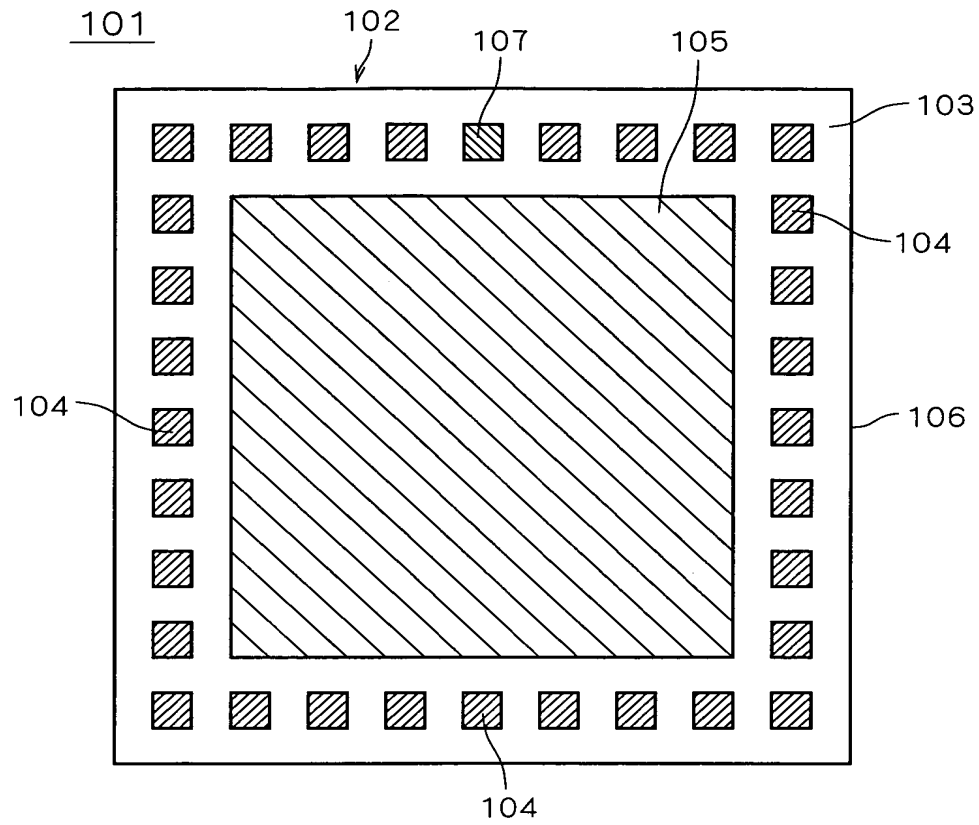


FIG. 12

